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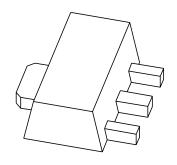
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Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



PBSS4250X 50 V, 2 A NPN low V_{CEsat} (BISS) transistor

Product data sheet Supersedes data of 2003 Jun 17 2004 Nov 08



50 V, 2 A NPN low V_{CEsat} (BISS) transistor

PBSS4250X

FEATURES

- SOT89 (SC-62) package
- Low collector-emitter saturation voltage V_{CEsat}
- High collector current capability: I_C and I_{CM}
- · Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements.

APPLICATIONS

- · Power management
 - DC/DC converters
 - Supply line switching
 - Battery charger
 - LCD backlighting.
- · Peripheral drivers
 - Driver in low supply voltage applications (e.g. lamps and LEDs).
 - Inductive load driver (e.g. relays, buzzers and motors).

DESCRIPTION

NPN low V_{CEsat} transistor in a SOT89 plastic package. PNP complement: PBSS5250X.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾
PBSS5250X	*1M

Note

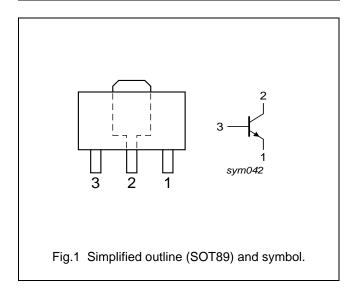
- 1. * = p: Made in Hong Kong
 - * = t: Made in Malaysia
 - * = W: Made in China.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{CEO}	collector-emitter voltage	50	V
I _C	collector current (DC)	2	Α
I _{CM}	peak collector current	5	Α
R _{CEsat}	equivalent on-resistance	160	mΩ

PINNING

PIN	DESCRIPTION	
1	emitter	
2	collector	
3	base	



ORDERING INFORMATION

TYPE NUMBER PACKAGE			
TIFE NOMBER	NAME	NAME DESCRIPTION	
PBSS4250X	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89

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PBSS4250X

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	50	V
V_{CEO}	collector-emitter voltage	open base	_	50	V
V _{EBO}	emitter-base voltage	open collector	_	5	V
I _C	collector current (DC)		_	2	Α
I _{CM}	peak collector current	limited by T _{j(max)}	_	5	Α
I _B	base current (DC)		_	0.5	А
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
		note 1	_	550	mW
		note 2	_	1	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	ambient temperature		-65	+150	°C

Notes

- 1. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; standard footprint.
- 2. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 1 cm².

THERMAL CHARACTERISTICS

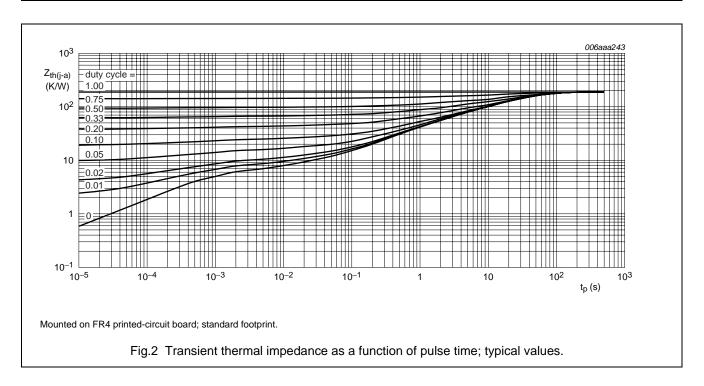
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air		
		note 1	225	K/W
		note 2	125	K/W
		note 3	90	K/W
		note 4	80	K/W
R _{th(j-s)}	thermal resistance from junction to soldering point		16	K/W

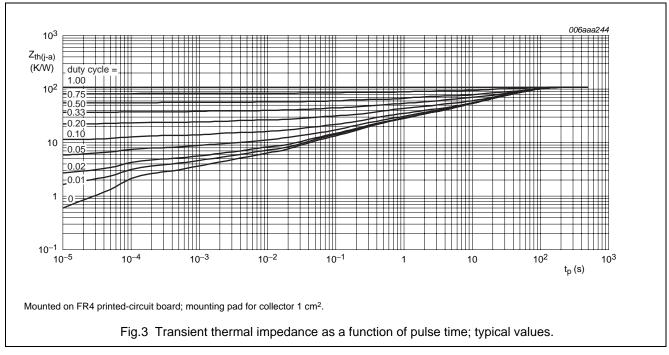
Notes

- 1. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; standard footprint.
- 2. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 1 cm².
- 3. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 6 cm².
- 4. Device mounted on a ceramic printed-circuit board 7 cm², single-sided copper, tin-plated.

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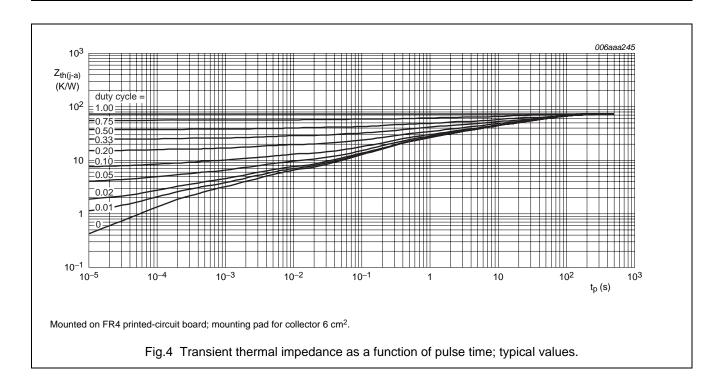
PBSS4250X





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PBSS4250X

CHARACTERISTICS

 T_{amb} = 25 $^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	V _{CB} = 50 V; I _E = 0 A	_	100	nA
		V _{CB} = 50 V; I _E = 0 A; T _j = 150 °C	_	50	μΑ
I _{CES}	collector-emitter cut-off current	V _{CE} = 50 V; V _{BE} = 0 V	_	100	nA
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	_	100	nA
h _{FE}	DC current gain	V _{CE} = 2 V			
		I _C = 0.1 A	300	_	
		I _C = 0.5 A	300	_	
		I _C = 1 A; note 1	300	_	
		I _C = 2 A; note 1	150	_	
V _{CEsat}	collector-emitter saturation	I _C = 0.5 A; I _B = 50 mA	_	90	mV
	voltage	I _C = 1 A; I _B = 50 mA	_	250	mV
		I _C = 2 A; I _B = 100 mA	_	380	mV
		I _C = 2 A; I _B = 200 mA; note 1	_	320	mV
R _{CEsat}	equivalent on-resistance	I _C = 2 A; I _B = 200 mA; note 1	_	160	mΩ
V _{BEsat}	base-emitter saturation voltage	I _C = 2 A; I _B = 100 mA	_	1.1	V
V _{BEon}	base-emitter turn-on voltage	V _{CE} = 2 V; I _C = 1 A	1.1	_	V
f _T	transition frequency	I _C = 100 mA; V _{CE} = 5 V; f = 100 MHz	100	_	MHz
C _c	collector capacitance	V _{CB} = 10 V; I _E = i _e = 0 A; f = 1 MHz	_	25	pF

Note

1. Pulse test: $t_p \leq 300~\mu s;~\delta \leq 0.02.$

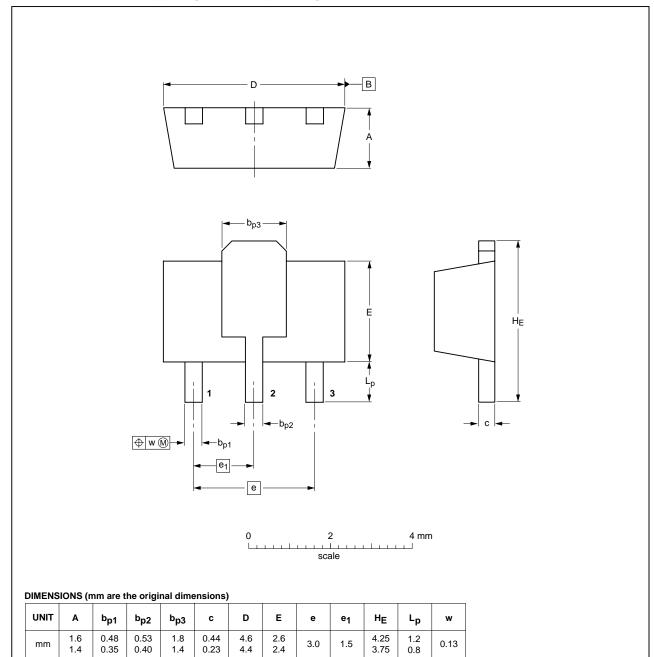
50 V, 2 A NPN low V_{CEsat} (BISS) transistor

PBSS4250X

PACKAGE OUTLINE

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads

SOT89



OUTLINE	OUTLINE REFERENCES		EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT89		TO-243	SC-62			04-08-03 06-03-16

50 V, 2 A NPN low V_{CEsat} (BISS) transistor

PBSS4250X

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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Printed in The Netherlands R75/02/pp9 Date of release: 2004 Nov 08 Document order number: 9397 750 13879



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